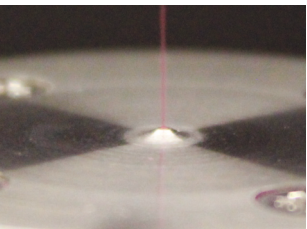




Pillarhouse
INTERNATIONAL

JADE HANDEX

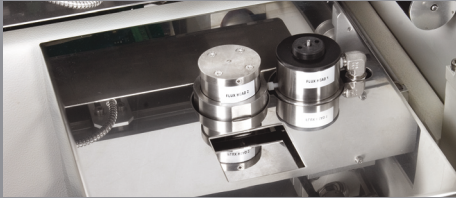
Quick load, twin PCB rotary table
selective soldering system



JADE HANDEX



Quick load, twin PCB rotary table selective soldering system

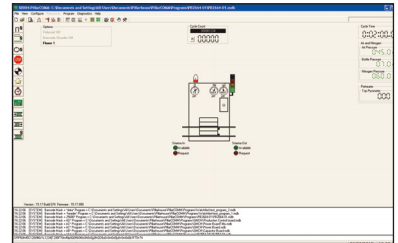


Designed to meet the needs of lean manufacturing, the Jade Handex offers high-speed flexible throughput at minimal cost. The Jade Handex is equipped with a revolutionary twin PCB rotary table transport system to allow simultaneous load/unload during product processing.

Our new generation, patented Drop-Jet design fluxer offers quick and effective flushing of the pressurised flux chamber. This helps to keep maintenance levels to a minimum whilst enabling use of higher solids content fluxes, as well as water-soluble fluxes. As part of the entry-level philosophy for this system, a newly designed low maintenance solder bath and pump mechanism has been developed which moves in three axes of movement, whilst not limiting access to the PCB. Solder is applied using proven technology through our AP-1 nozzle design or custom specialised nozzles, incorporating patented spiral solder return-to-bath technology, offering reduced solder balling potential. As with more sophisticated Pillarhouse systems, the soldering process is enhanced by an inerted hot Nitrogen curtain, providing an inert atmosphere for the soldering process, assisting the prevention of oxidation. This process provides a local pre-heat to the joint, thus reducing thermal shock to localised components.

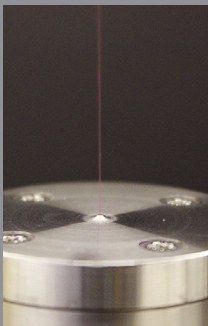


SLIDE IN/OUT BOTTOM SIDE IR PRE-HEAT

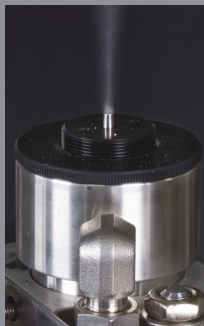


OPERATION

The Jade Handex is controlled by a PC, through PillarCOMM, a Windows® based 'Point & Click' interface with PCB image display, as illustrated above. Additionally, our optional PillarPAD offline package allows the operator to produce programs independently from the machine using Gerber data.



DROP-JET FLUX HEAD



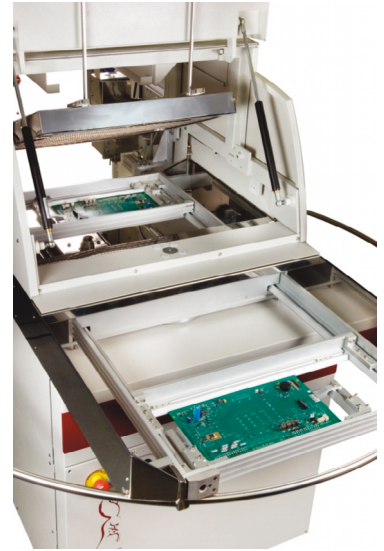
ULTRASONIC FLUX HEAD



BOTTOM SIDE SLIDE IN/OUT IR PRE-HEAT



TWIN INDEPENDENT FLUX BOTTLE ASSEMBLY



JADE HANDEX
ADJUSTABLE TOOLING
ROTATE MECHANISM

STANDARD FEATURES

- Integral PC & Machine Mounted TFT Monitor
- Inerted Nitrogen System
- Auto Motorised Solder Wire Feed & Level Detect
- Drop-Jet Fluxer
- Internal Fume Extraction
- Colour Programming Camera
- Rotary Indexing Table with Twin Work Holding Positions
- Manual Fiducial Correction System
- PillarCOMM Windows® based 'Point & Click' interface
- Thermal Nozzle Calibration System using Integrated Setting Camera (requires manual correction)
- Flux Level Sensor
- Solder Wave Height Measurement
- Pump RPM Monitoring
- Auto Nozzle Conditioning System
- Process Viewing Camera
- Multilevel Password Protection System
- Light Stack Tower
- Lead-Free Compatibility
- 9 AP Solder Nozzle Tips
- Day-To-Day Service Kit

MONITORING OPTIONS

- Flux Presence Sensor - Thermistor Style
- Flux Spray and/or Flow
- O₂ PPM

SYSTEM OPTIONS

- Ultrasonic Fluxing
- Dual Drop-Jet/Ultrasonic Fluxing
- Top & Bottom Side Slide In/Out Instant IR Pre-Heat
- Closed-Loop Pyrometer Temperature Control
- Solder Reel Identification
- Solder Bath Coding (identifies correct bath for program)
- Automatic Fiducial Correction System
- Laser PCB Warp Correction
- PillarPAD Offline Programming System
- Encoders on X, Y and Z Axis



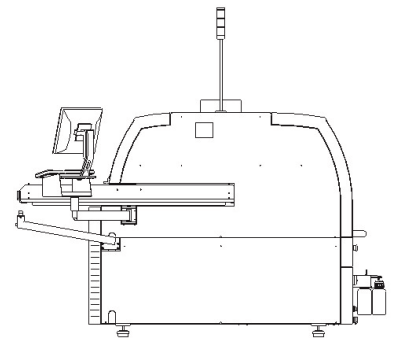
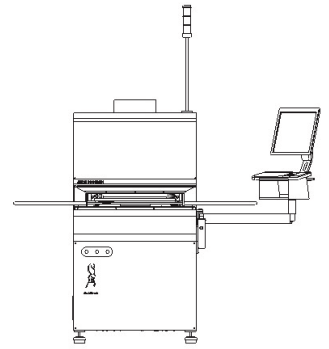
ADDITIONAL SYSTEM OPTION - PillarCARE
Pillarhouse's comprehensive after-sale service and process programme, available for all machines



JADE HANDEX

SPECIFICATIONS

Height:	1627mm / 64" - excluding light stack
Width:	1900mm / 74"
Depth:	2508mm / 90"
Board size:	Max. - 457mm x 508mm / 18"x 20"
Edge clearance:	Above/below 3mm
Height clearance:	Above 95mm / below 45mm nominal
Solder:	Most commonly used solder types - includes lead-free
Solder pot capacity:	15kg standard - 25kg large bath
Applicators:	AP style - 2.5mm to 16mm dia. Extended AP style - 2.5mm to 20mm dia. Micro Nozzle - 1.5mm to 2.5mm Jet-tip style - 6mm to 40mm dia. Jet-Wave nozzle - up to 25mm width Special dedicated nozzles available upon request
Flux:	Low maintenance Drop-Jet system. Low solids (below 8%), no clean flux, pressurised and inerted system, optional water-soluble system available.
X, Y & Z axis resolution:	0.15mm
Repeatability:	+/- 0.05mm.
Nitrogen supply pressure:	5 bar / 72 psi
Nitrogen usage:	30-100 litres/min. - solder nozzle configuration dependent
Nitrogen purity:	99.995% or better
Air supply pressure:	5 bar / 72 psi
Air usage:	10 litres/min. / 0.35 CFM
Power Supplies:	Single phase + PE
Voltage:	230V
Frequency:	50/60Hz
Power:	10.5 kVA max. - machine configuration dependent
Programming:	PillarCOMM Windows® based 'Point & Click' interface



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